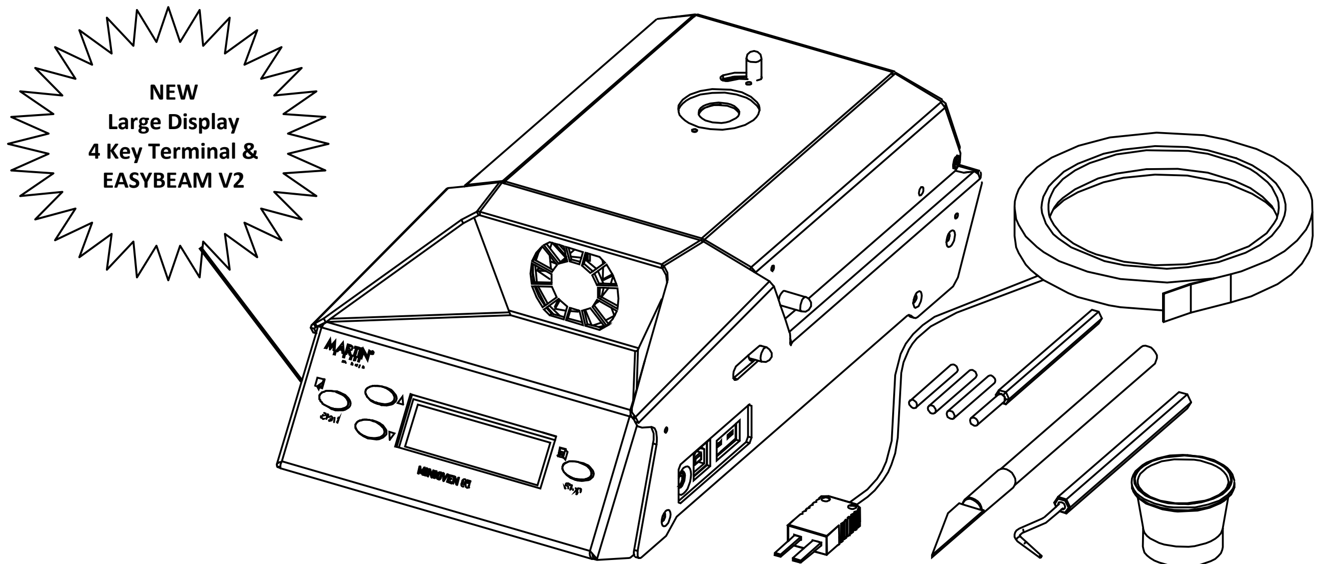
REWORK TECHNOLOGY

MARTIN®

a finetech company

MINIOVEN 05



HB00.0025 MINIOVEN 05

The MINIOVEN 05 is a compact and robust table-top device specially designed for reballing of BGAs and prebumping of QFN components. Its highly efficient hybrid heating technology heats-up the electronic components like in a standard reflow oven: Gentle and simultaneously from all sides and guarantees repeatable process results with high yield. MINIOVEN 05 is perfect for use in both production and R&D environment.

The large display and the 4 button front panel layout enable fast set-up and administration of up to 25 reballing profiles which can be saved in the device. Profiles can be taught with the devices auto profiler software. For highest confidence of teaching procedure, the MINIOVEN 05 device use readings from a second temperature sensor which is connected to the oven and attached next to BGA and measures the IC temperature. An inlet for use of process gasses like i.e. nitrogen is factory pre-set.

The free of charge PC software EASYBEAM V2 can be used to download profiles, i.e. for back-up and upload of reballing profiles i.e. from a production server easily. EASYBEAM V2 connects via USB to the MINIOVEN 05 and also may display temperature plots of the two sensors and allows optimization of profile parameter to fit user expectations perfectly.

Aside of a wide range of tooling and accessories for BGA reballing, holders, fixtures and stencils for QFN prebumping are available too. Stencils for a wide selection of QFN components are available from shelf.

Basic Equipment

- MINIOVEN 05 Base Unit
- Sensor for Temperature (K-Type)
- Cutter Knife
- SMD Hook
- Cleaning Pen with three spare inserts
- Capton Tape
- Magnifier
- Power Cable
- Manual

Technical Data

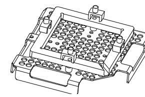
System power consumption:	550 VA
Power heater:	500 W, 4 x IR-Lamps
Size heater:	105 x 130 mm²
Number of Temperature Sensors:	1 x internally inst. & 1 x external opt.
Number of profiles:	25 entries on device
Rec. max. component Size:	55 x 55 x 4 mm³
Mains:	1 Phase, 230 VAC
System dimensions:	150 x 300 x 85 mm³

MINIOVEN 05

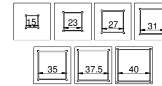
Application Sets

LW50.9001 **Reball-04 Set eco Standard**

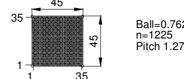
LW40.0236 Reballing Fixture BGA 45*45mm for MO-04
4 downholder clips



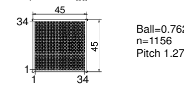
LW40.0500 Reballing Frame Set BGA
for all (98%) types of BGA, 7 pieces



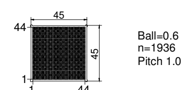
LW40.0543 Reballing Mask BGA 45*45mm
n=1225 / Pitch=1,27 / Grid=35*35 / Ball=0,762



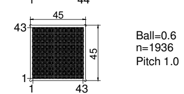
LW40.0686 Reballing Mask BGA 45*45mm
n=1156 / Pitch=1,27 / Grid=34*34 / Ball=0,762



LW40.0688 Reballing Mask BGA 45*45mm
n=1936 / Pitch=1,00 / Grid=44*44 / Ball=0,6

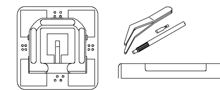


LW40.0687 Reballing Mask BGA 45*45mm
n=1849 / Pitch=1,00 / Grid=43*43 / Ball=0,6

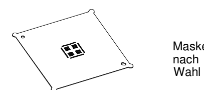


SF29.0002 **Prebump-04 Set QFN**

HB50.0005 Tooling and Fixture for QFN Prebumping
printer, holder, squeegee, tweezers

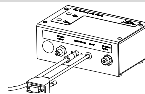


LWxx.xx11 Prebumping Mask + Frame QFN
Type of standard QFN mask on request



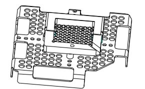
Options

HB00.0112 Switch Box Process Gas
for MINIOVEN 05 with connection set

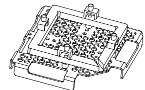


HB00.4005 Process Gas Connection Set
for MINIOVEN 05

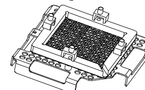
LW40.0251 Reballing Fixture CSP 27*27mm for MO-04
Standard



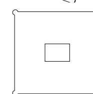
LW40.0236 Reballing Fixture BGA 45*45mm for MO-04
4 downholder clips



LW40.0237 Reballing Fixture BGA 45*45mm
with 4 clips and support grid (to be used for PS3)

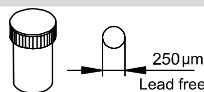


LWxx.xxx9 Reballing Frame CSP
size for CSP type your choice

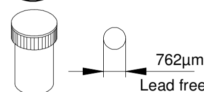


Consumables

VD90.5104 Solder balls, 50,000 pc, leadfree CSP
Sn96.5Ag3Cu0.5 250µm (=3g)



VD90.5101 Solder Balls, 50,000 pcs., lead free BGA
Sn96,5Ag3Cu0,5 762µm (=86g)



HT00.0009 Flux Pen lead free
0405 C, no clean, RELO